

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE (TOLERANCE ±0.05)

PAD AREA
 CONNECTOR OUTLINE
 NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics
Dimensions:14.10LX13.30WX1.50H mm
Weight:Approx 0.60±0.2g
Durability:2,000 cycles min.

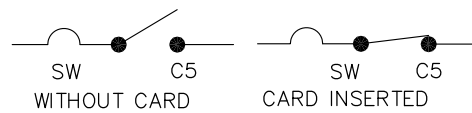
2.Electrical Characteristics
Contact resistance:50mΩ typical,
100mΩMax
Insulation resistance:>1000MΩ/500V DC

3.Solderability
Vaporphase:215°C, 30sec.Max
IR reflow:260°C,5sec.Max
Manual soldering:370°C.3sec.Max

4.Environmental Characteristics
Operating temperature:-40°C~+85°C
Operating humidity:10%~+95%RH

| Micro SIM CARD | |
|----------------|----------|
| Pin No. | NAME |
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C4 | Reserved |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |
| C8 | Reserved |

| ELECTRIC FUNCTION | DETECT SWITCH |
|-------------------|---------------|
| WITHOUT CARD | OPEN |
| CARD INSERTED | CLOSED |



SWITCH OPERATION DIAGRAM

| ITEM | PART NAME | Q'TY | MATERIAL | FINISH |
|------|--------------|------|-----------------------|--------------------------|
| 1 | HOUSING | 1 | Hi-temp Thermoplastic | Black UL94V-0 |
| 2 | DATA CONTACT | 8 | Copper Alloy | Contact area:Gold plated |
| 3 | SW | 1 | Copper Alloy | Contact area:Gold plated |
| 4 | SHELL | 1 | Stainless Steel | Solder area:Gold plated |

Unless otherwise specified, other tolerance are:

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **Micro SIM Card Connector**

MODEL NO: **MUP-C7093-01**

TYPE: **H1.50mm 8PIN**

| | | | | | |
|------------------|------|-------|----------|-------------------|-----------------|
| PROJ. | UNIT | SCALE | DRAWN | Henry Jan.03.2017 | DWG NO.: |
| | mm | 1:1 | CHECKED | Henry Jan.03.2017 | DWG-C7093-01-01 |
| CUSTOMER DRAWING | | | APPROVAL | Simon Jan.03.2017 | SHEET |
| | | | | | 1/1 |
| | | | | | REVISION |
| | | | | | 2 |



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